



Ampoc Far East Co., Ltd

揚博科技股份有限公司  
Ampoc Far-East Co., Ltd.

股票代號：2493



2019/09/09



Ampoc Far East Co., Ltd

1. Ampoc Profile
2. Company History
3. Products Introduction and Application
4. Financial Information
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Ampec Far East Co., Ltd

# 1. Company Profile

**Company : AMPOC Far-East Co., Ltd.**

**Address : 17F., No.171, Sung-Teh Road,  
Taipei, Taiwan**

**Tel : (02) 2726-2220**

**E-mail : 1service@ampoc.com.tw**

**Responsible Person :**

**Chairman, Mr. Ronald S. Su**

**C.E.O., Mr. Alden Chiao**

**Since : November 1, 1980**

**Paid-up Capital : NT\$ 1,144 Million**

**Employee : 280 people**



*Mr. Ronald S. Su*



## 2. Company History

### AMPOC's History



2006/12

- Ampec merged Yang Shin Investment Co., Ltd which Ampec owned 100%.

2002/01

- Ampec was approved to list on the Taiwan Stock Exchange, Stock Code: 2493.

2001/06

- Stock dividend was issued, resulting in total capital of NT\$905 million.

2000/10

- Paid-in capital was increased to NT\$73.7 million.

1999/12

- Ampec merged with TTCM and issued additional 21,107,000 shares, paid-in capital increased to NT\$57.1 million.

1998/12

- Ampec was approved as public company.  
Ampec was engaged in capitalization of NT\$10.2 million, paid-in capital increased to NT\$30 million.

1998/03

- Ampec established the inspection lab. with precision instruments to enhance our service quality.

1997/03

- Ampec purchased the office which located at 17F, No.171, Sung-Teh Rd., Sinyi District, Taipei.

1987/05

- TCM in Japan which was a master manufacturer of PCB Wet Process established TTCM in CHUNG-LI industrial zone, Taiwan. Ampec invested in TTCM and obtained the sole global distribution agreement except in Japan.

1980/11

- Ampec was founded in Taipei with initially registered capital of NT\$1 million.



# 3. Products Introduction and Applications

## □ Application

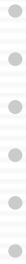
- FEOL
- Advanced Package
- MEMS

## □ Product

- Ampoc Wing Vertical System
- Conventional horizontal System
- Laser Heater TC Bonder



Ampoc Far East Co., Ltd



# Application





# Applications - core strategies for development

- ✓ Flip chip bumping chemical
- ✓ 3D-IC · FOWLP High speed plating chemical
- ✓ Wafer bumping UBM high selective etchant
- ✓ High resolution PR
- ✓ Hard Mask

FEOL

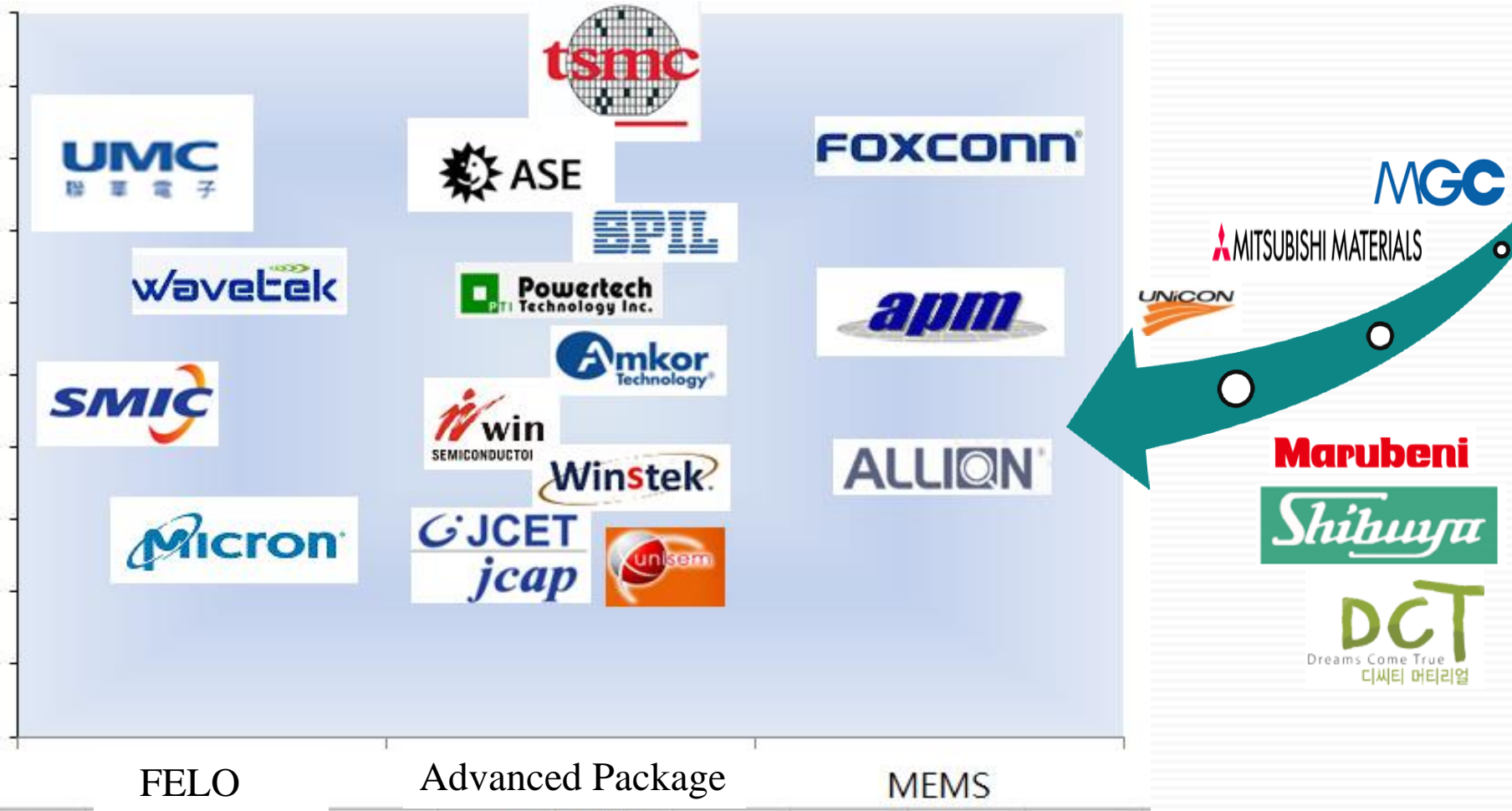
Advanced Package

- ✓ Leadframe metal finish
- ✓ QFN leadframe EDPR
- ✓ fine pitch MLO for probe card

MEMS



# Main Customer & Partner







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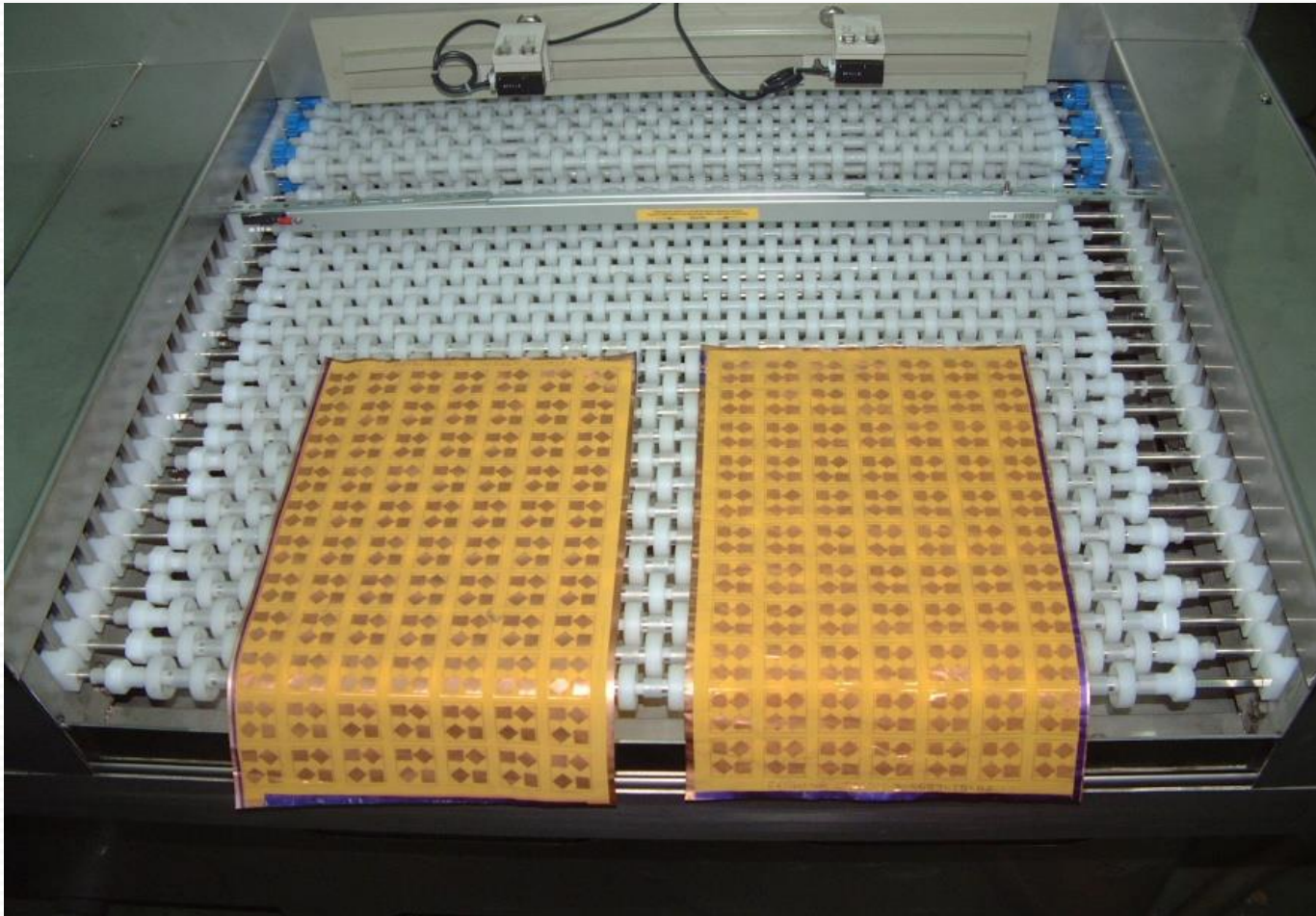


# Products Introduction





## Conventional horizontal System





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# ABF Ampec Wing Vertical System



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*Ampec Far-East Co., Ltd*

ABF載板製程用

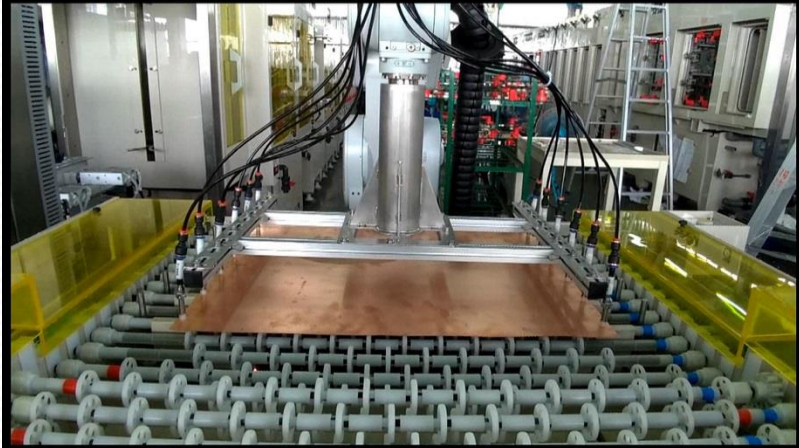
AMPOC WING垂直顯影線





# ABF載板垂直顯影系統 (Ampoc Wing)

自動上料系統



ABF 電路板載入顯影機進行藥液處理



自動換夾系統



ABF 電路板進行第2次藥液處理



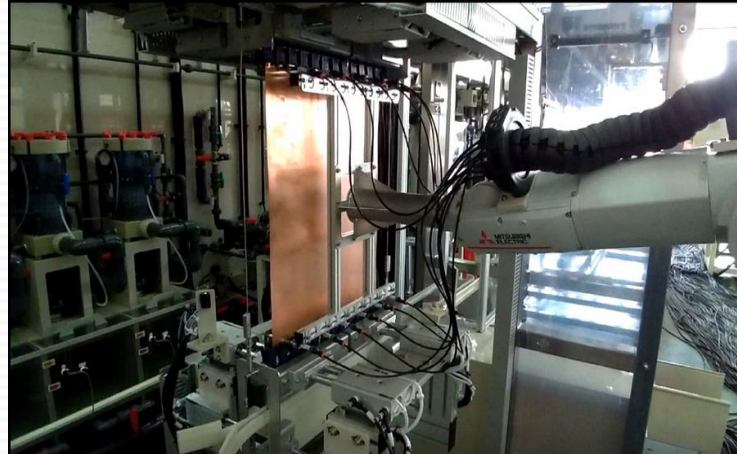


# ABF載板垂直顯影系統 (Ampoc Wing)

電路板進行U型自動迴轉



ABF電路板處理完成自動下料系統

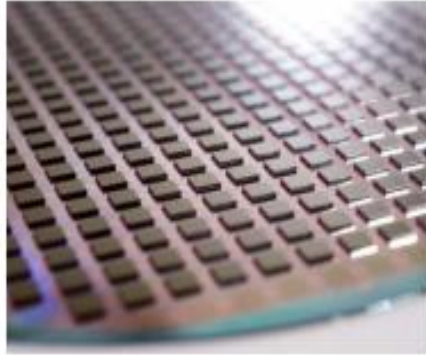


複合尺寸自動換框生產系統





# Laser Heater TC Bonder



- Fast heating and cooling
- Low thermal expansion
- Localized heating





# Market trend and outlook in 2019

Growth of semiconductor and PKG industries turns out to be weak, due to the sluggish demand in 2019 H1. Revising down of smart phone, automobile and industrial demands, price drop of cryptocurrencies, US-China trade war, these are factors lead to weak demand of semicon products. Semicon market inclines to deplete inventory continuously in H1. Electronic industry is seen to be suffered from great impact; however, this could be considered as a new chance for AMPOC's agency business which aims at non-US products. Due to the trade war impact, our target in H2 remains to be China market.

With its long experience in Taiwan electronics market, advantages regarding equipment manufacturing and connections among supply chain of customers, AMPOC holds its belief and vision and keeps on cultivating the new market. Furthermore, AMPOC is aggressively arranging its tactical planning regarding Semiconductor front-end, Advanced packaging and MEMS markets.



## Taiwan PCB industry review 2018 and outlook 2019

- 2018 Global PCB output value reaches USD 69.1 billion and hits a historical.
- 2018 top 3 PCB manufacturing countries:
  - Taiwan : 31.3% = (31.3%)
  - China : 23.0% ↑ (17.4 %)
  - Japan : 19.1% ↓ (20.5%)

Although in 2018 Taiwan has a share of 31.3% and leads the global market, China moves to the second position based on a 23% market share and rapid growth rate. China makers show no fear regarding the threat of trade war and further positively invest more on high density and high layer count products. Meanwhile, these makers expand their capability and increase their scope of business by frequently merging firms as well.

- Growth drives of PCB industry in 2018 : IC substrate, automotive electronics and smart watch and bluetooth headset.
- Estimated PCB plants expansion in 2019 H1 : ABF substrate, FPC and rigid flex board. Applications: smart phone, automotive electronics, IoT and networking communication.
- 2019 Indicators of equipment demand :
  1. advanced ABF substrate manufacturing
  2. China makers' diversification strategy of high-end products, including HDI, FPC, SLP and 5G substrate
  3. Automotive electronics





## 4. Financial Information

Condensed Statement of Comprehensive Income from 2017 to 2019 H1

Unit: NT\$ thousands (Except EPS: NT\$)

Item	Year	2017	2018	2019 H1
Net Revenue		2,281,684	2,400,520	1,241,236
Gross profit		677,644	765,833	332,522
Gross margin(%)		29.70	31.90	26.79
Operating income		310,926	423,299	175,076
Net income after tax		247,036	342,985	135,911
EPS		2.16	3.00	1.19



## Condensed Balance Sheet from 2017 to 2019 H1

Unit: NT\$ thousands (Except EPS: NT\$)

Item	Year	2017	2018	2019 H1
<b>Current Assets</b>		<b>2,493,281</b>	<b>2,713,049</b>	<b>2,849,193</b>
<b>Non-current Assets</b>		<b>752,903</b>	<b>758,096</b>	<b>748,407</b>
<b>Total Assets</b>		<b>3,246,184</b>	<b>3,471,145</b>	<b>3,597,600</b>
<b>Current Liabilities</b>		<b>860,792</b>	<b>938,712</b>	<b>1,207,320</b>
<b>Non-current Liabilities</b>		<b>130,608</b>	<b>108,930</b>	<b>117,786</b>
<b>Total Liabilities</b>		<b>991,400</b>	<b>1,047,462</b>	<b>1,325,106</b>



## Financial Analysis from 2017 to 2019 H1

Item	Year	2017	2018	2019 H1
<b>Debts Ratio (%)</b>		<b>30.54</b>	<b>30.18</b>	<b>36.83</b>
<b>Current Ratio(%)</b>		<b>289.65</b>	<b>289.02</b>	<b>235.99</b>
<b>Average Inventory Turnover (Times)</b>		<b>2.09</b>	<b>1.89</b>	<b>2.22</b>
<b>Return on Equity (%)</b>		<b>11.02</b>	<b>14.66</b>	<b>5.79</b>



## 5.Future outlook

- Business development direction
- Competitive Advantage
- Unfavorable factors and countermeasures

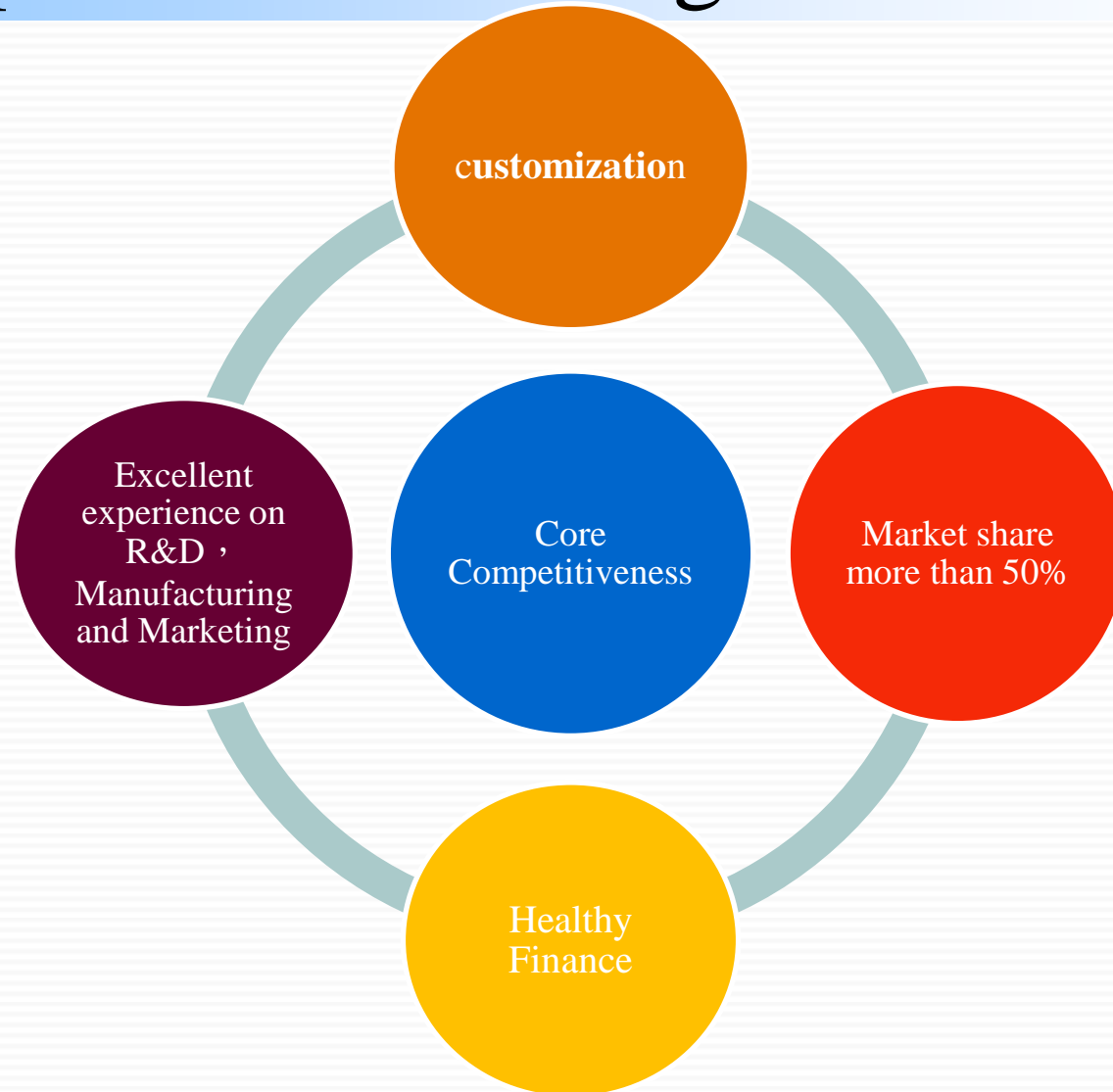


# Business development direction

- Developing innovative technology equipment
  - HDI PCB substrate-like process equipment
  - FPCB and Rigid PCB process equipment
  - Automotive substrate process equipment
  - Intelligent equipment
- Developing new market
  - Southeast Asia
  - India



# Competitive Advantage



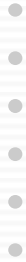


## Unfavorable factors and countermeasures

- Low price competition
  - Ampoc is going to keep R&D investment and continue to develop all kinds of new technology equipment to receive our customer's trust and orders.
- Increase of manpower and material
  - Ampoc is going to reduce high price material through widely usage of computer and robot.



Ampoc Far East Co., Ltd



*Thank you*

*The End*

